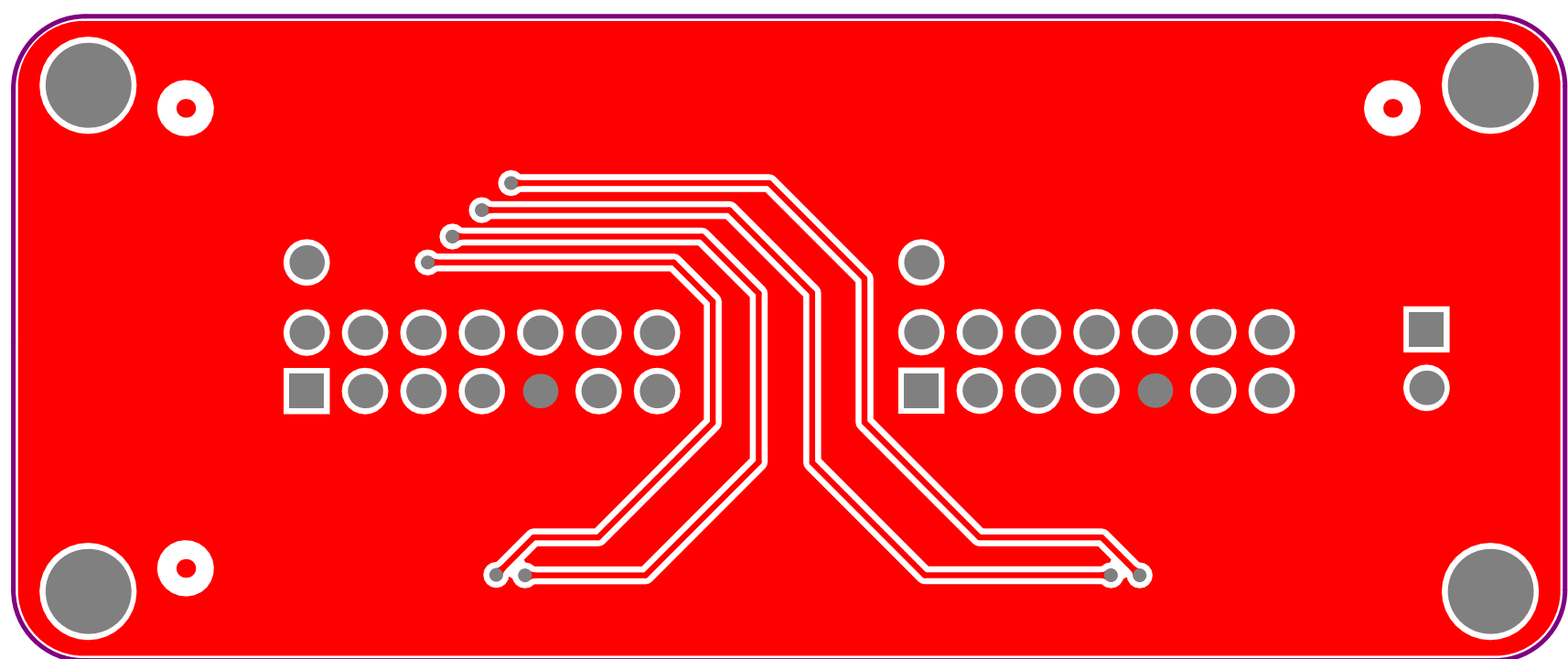
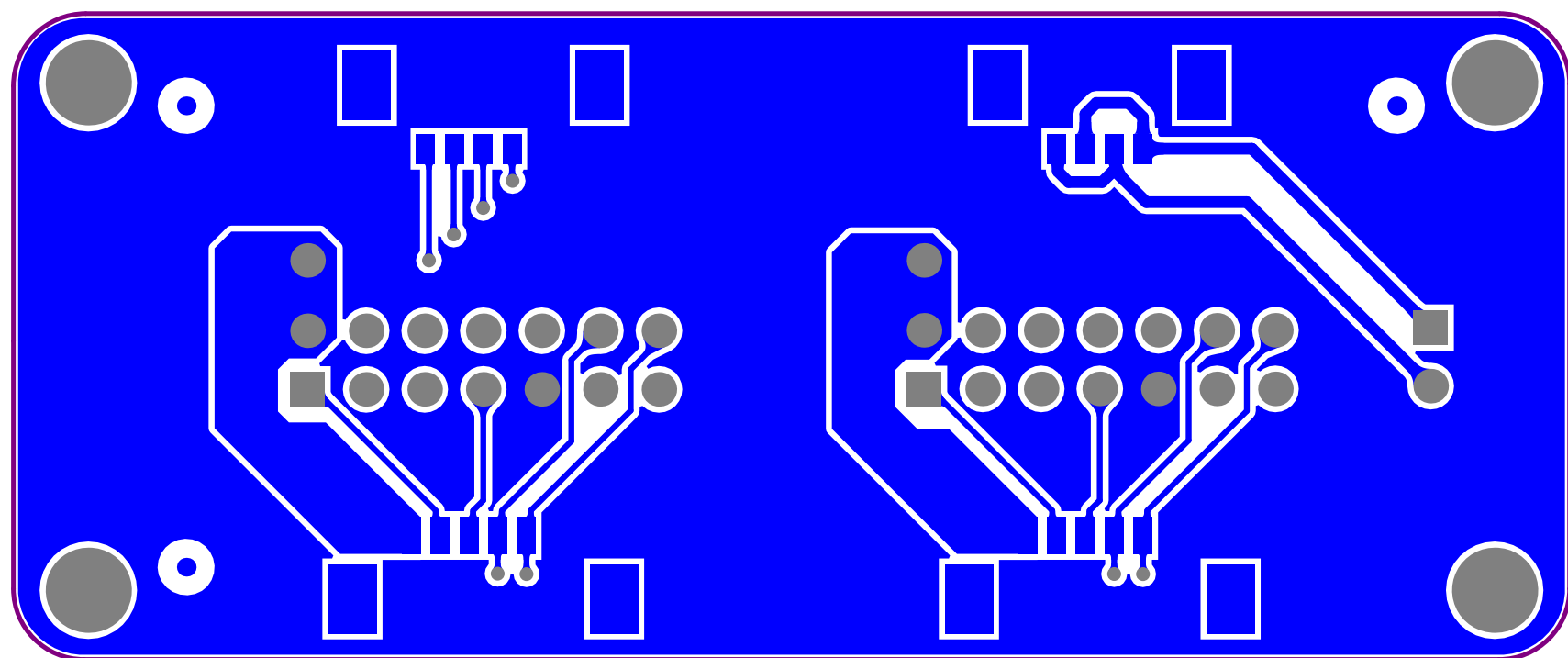


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
	Dielectric 1	FR-4	1.500mm	4.8	
2	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				



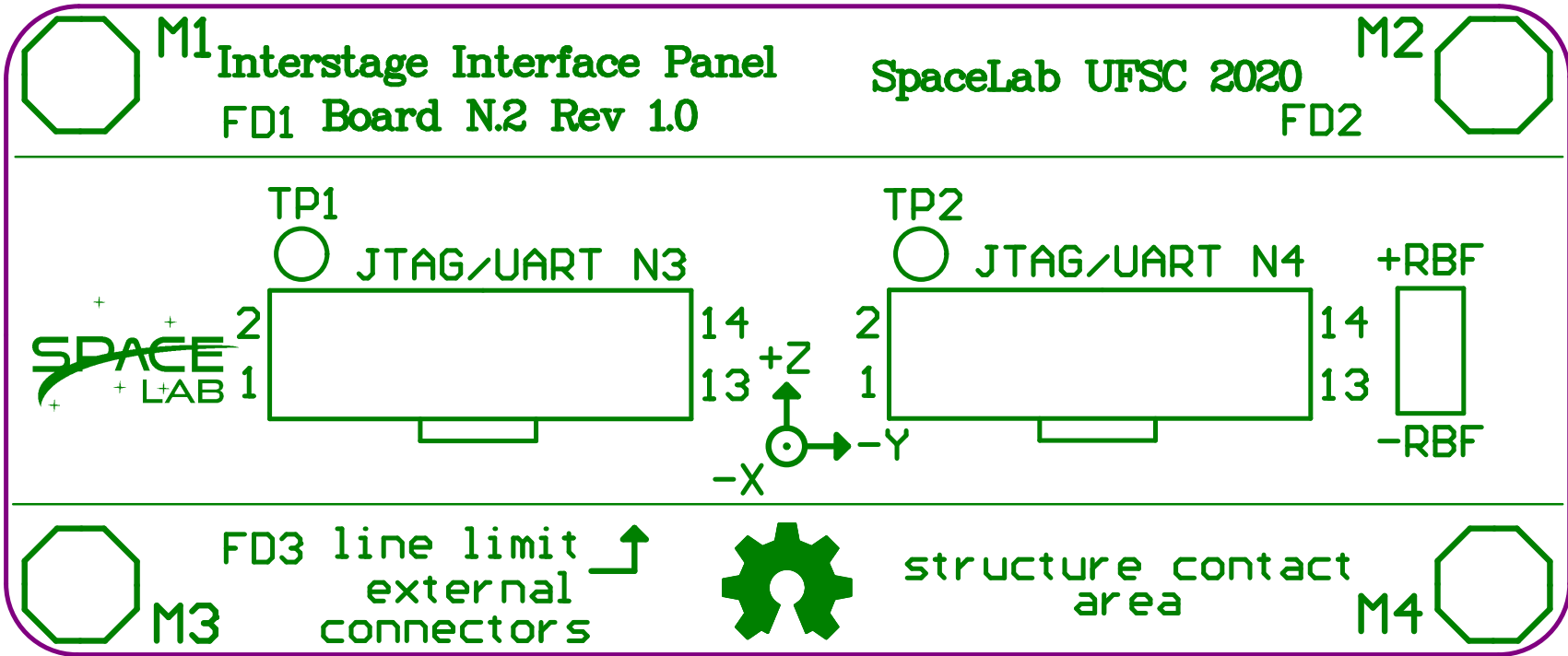
TITLE: IIP N.2 BOARD RBF		REV: 1.0	DATE: 02/07/2020
MATERIAL: FR4	Silkscreen color: white	Project: IIP	
Board Thickness: 1.6mm	Layers: 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC	
PCB Surface: HASL	Drawing: Yan C. de Azeredo		

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
	Dielectric 1	FR-4	1.500mm	4.8	
2	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				



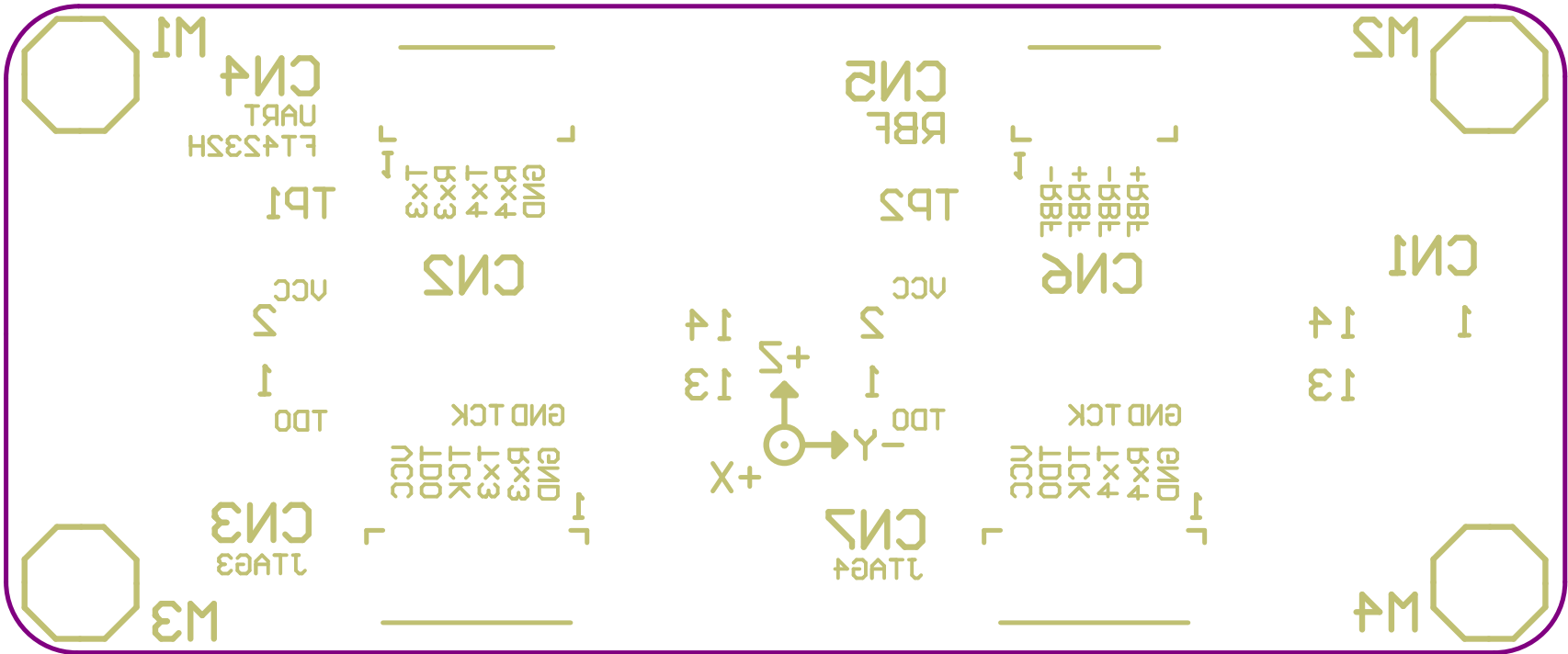
TITLE: IIP N.2 BOARD RBF		REV: 1.0	DATE: 02/07/2020
MATERIAL: FR4	Silkscreen color: white	Project: IIP	
Board Thickness: 1.6mm	Layers: 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC	
PCB Surface: HASL	Drawing: Yan C. de Azeredo		

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
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2	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				



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PCB Surface: HASL	Drawing: Yan C. de Azeredo		

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
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PCB Surface: HASL	Drawing: Yan C. de Azeredo		

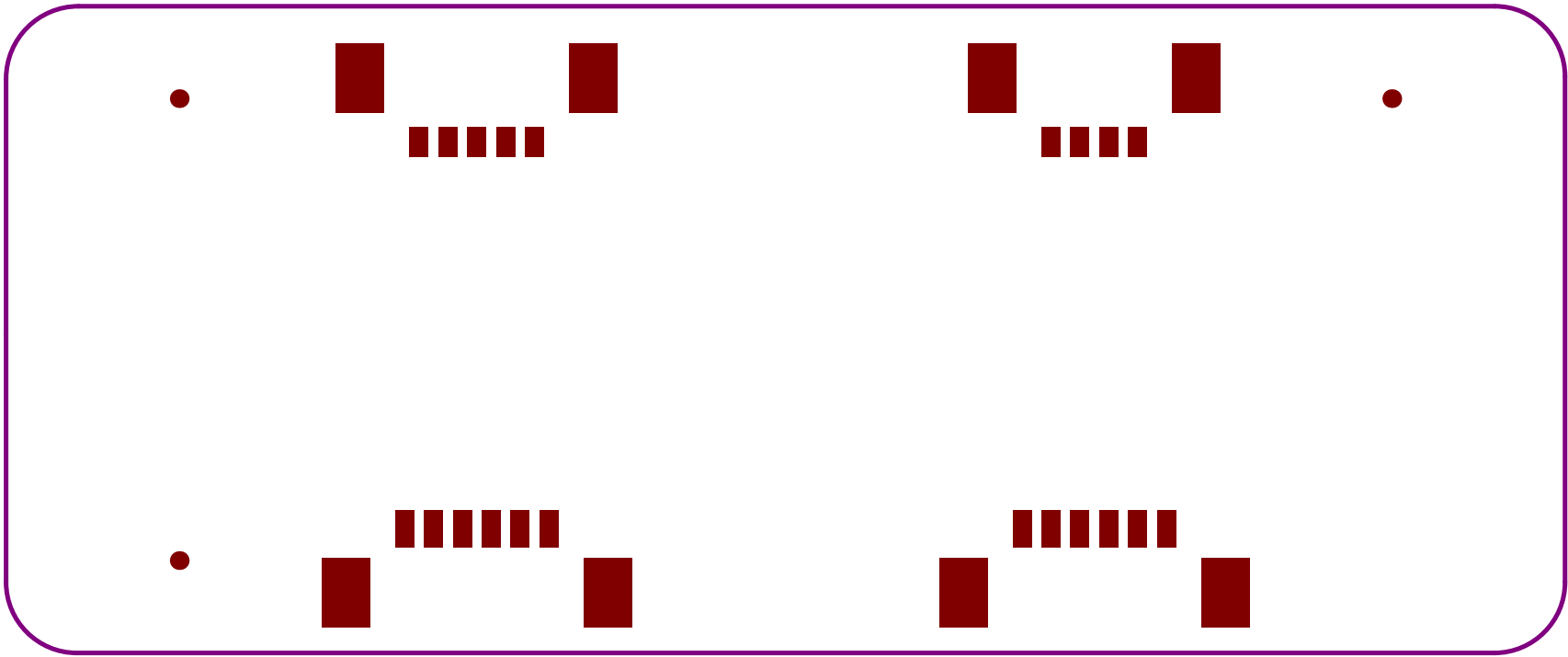


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
	Dielectric 1	FR-4	1.500mm	4.8	
2	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				



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MATERIAL: FR4	Silkscreen color: white	Project: IIP	
Board Thickness: 1.6mm	Layers: 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC	
PCB Surface: HASL	Drawing: Yan C. de Azeredo		

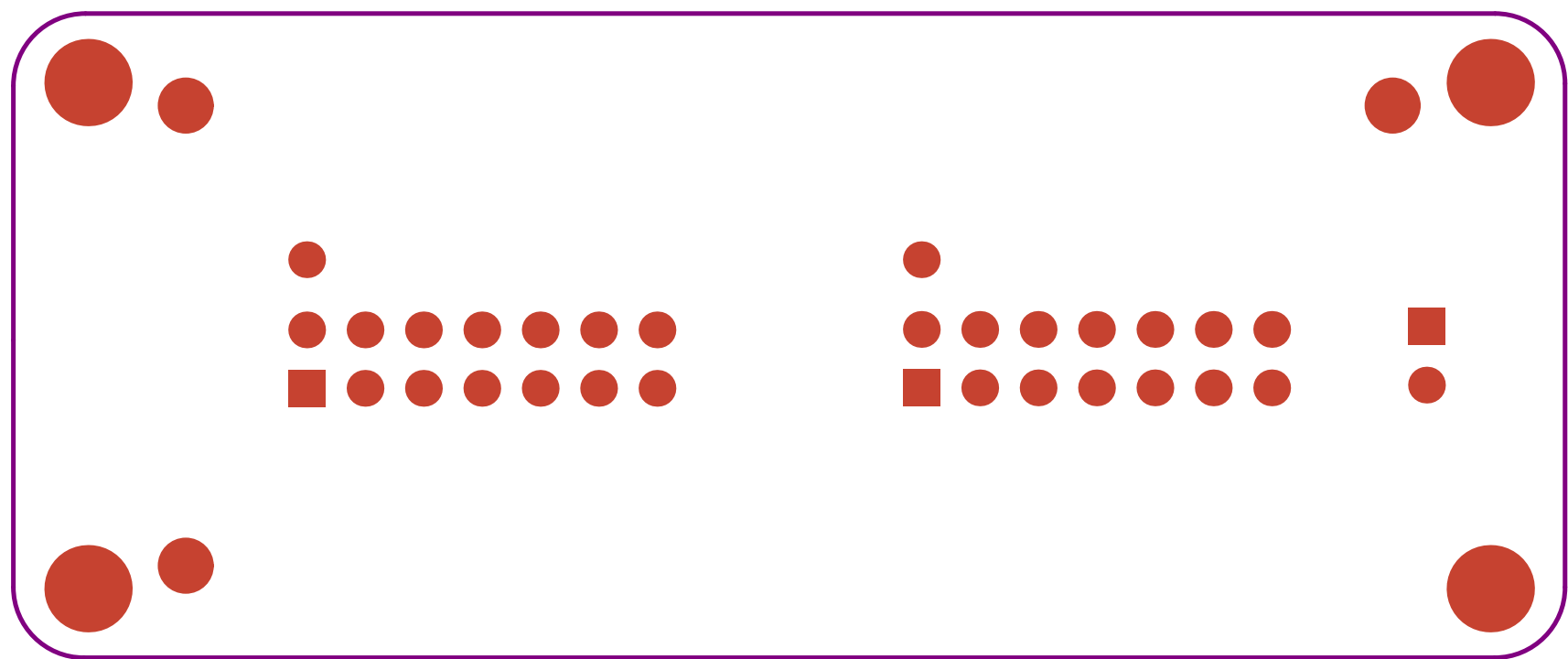
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
	Dielectric 1	FR-4	1.500mm	4.8	
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	Bottom Overlay				



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PCB Surface: HASL	Drawing: Yan C. de Azeredo		

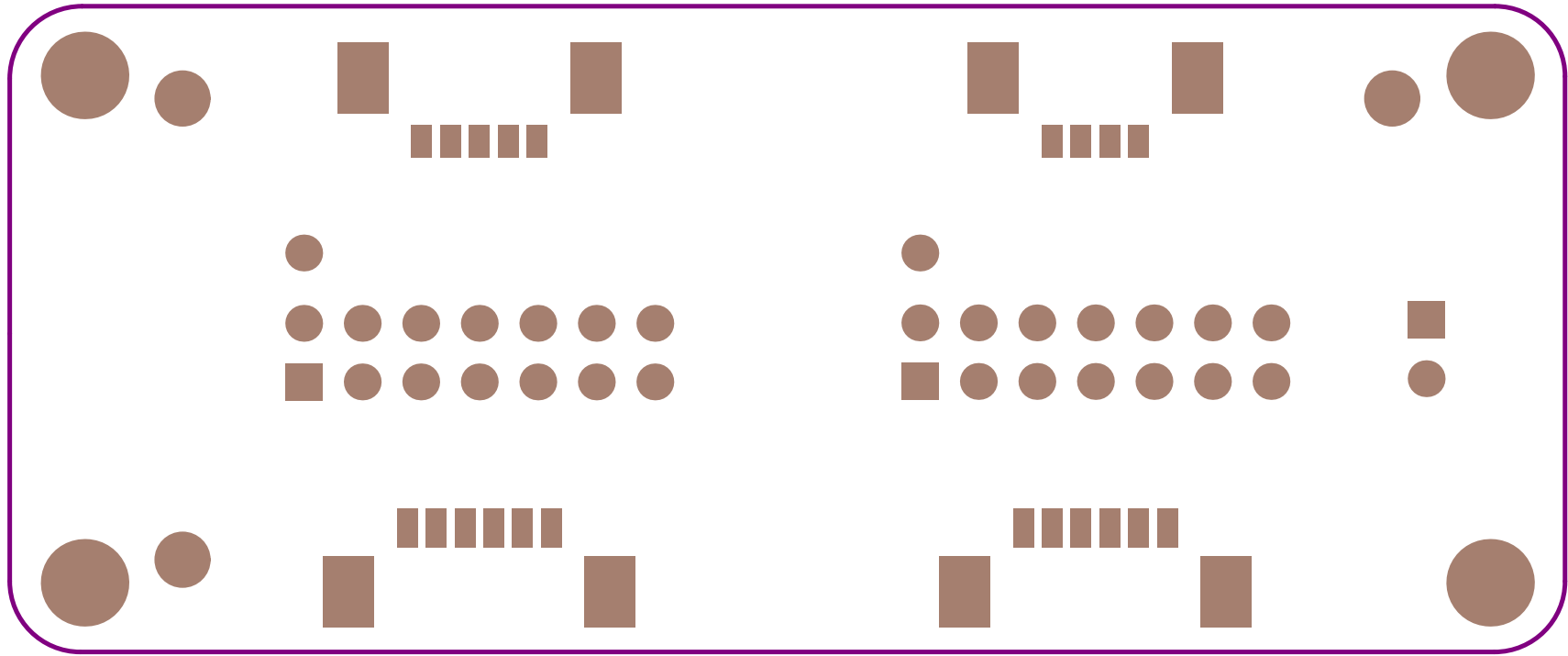


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
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	Bottom Overlay				



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2	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				

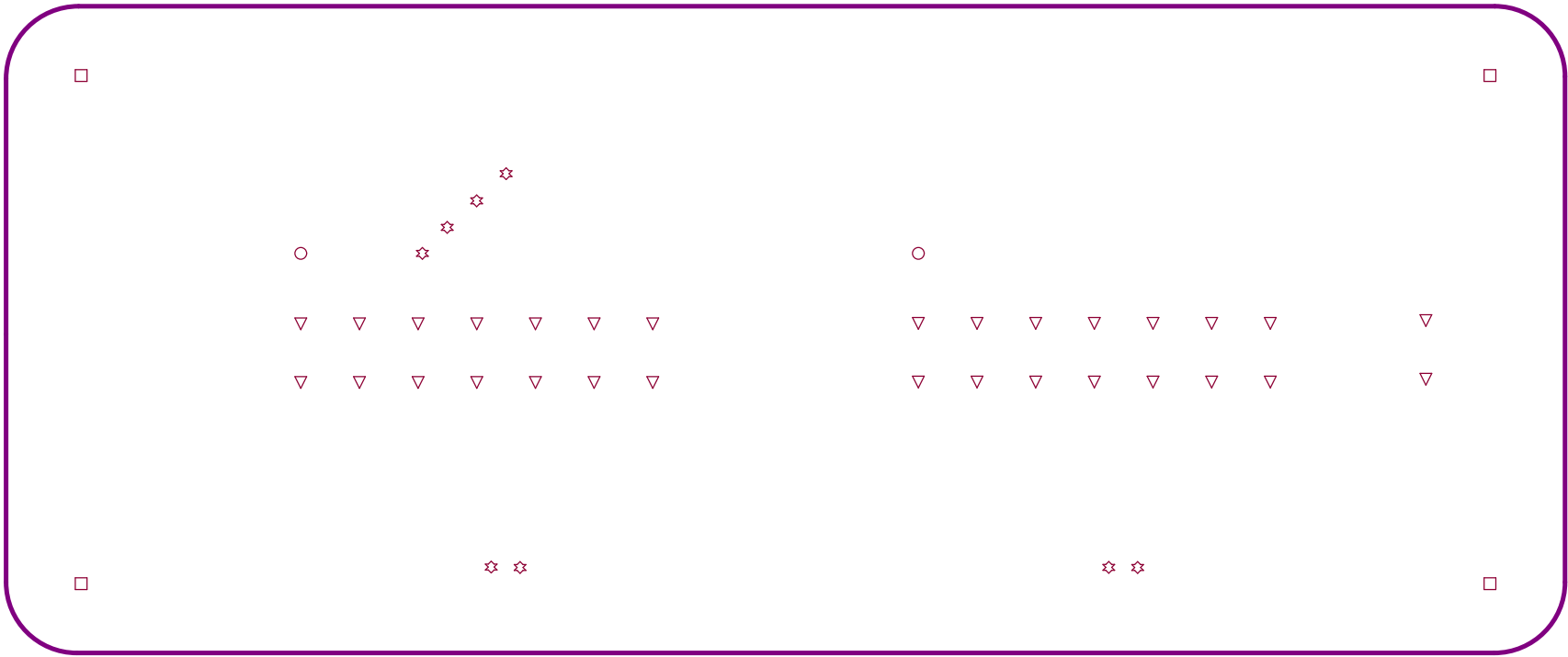


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MATERIAL: FR4	Silkscreen color: white	Project: IIP	
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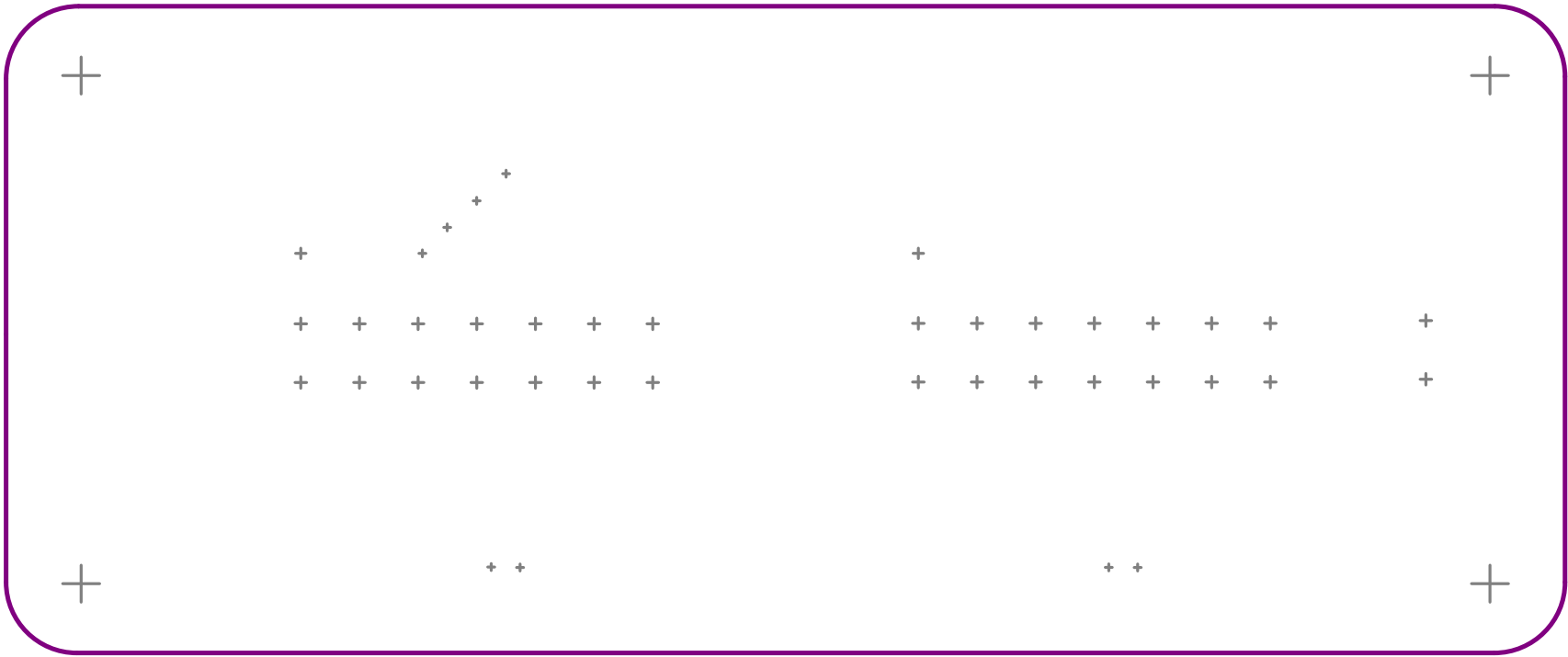
Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
☆	8	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h30m0mx0
○	2	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c150h90
▽	30	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
□	4	3.200mm (125.98mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c370h320
	44 Total							

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				[Hatched Pattern]
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		[Hatched Pattern]
	Dielectric 1	FR-4	1.500mm	4.8	
2	Bottom Layer	Copper	0.036mm		[Hatched Pattern]
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				[Hatched Pattern]



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Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
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